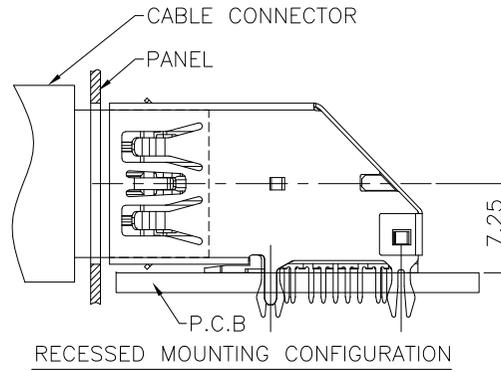
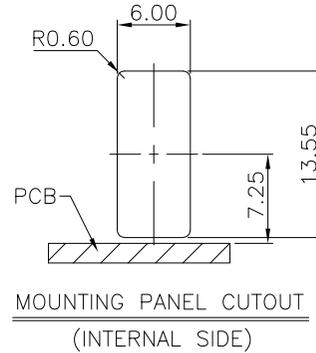
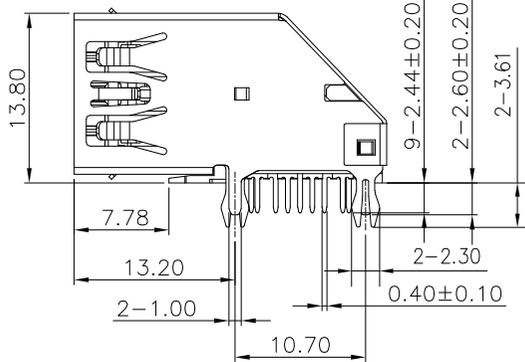
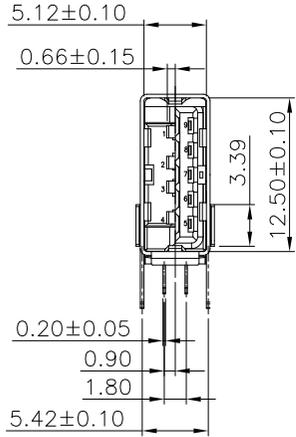


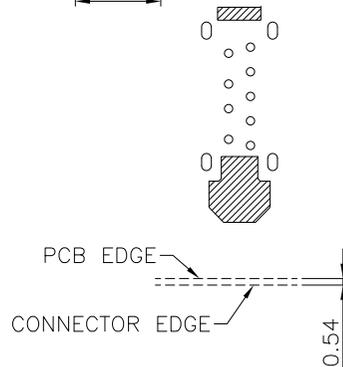
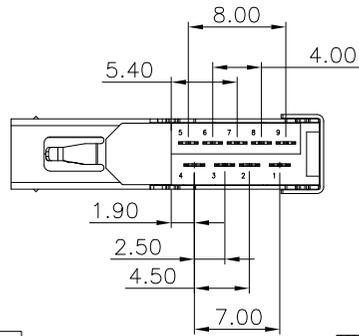
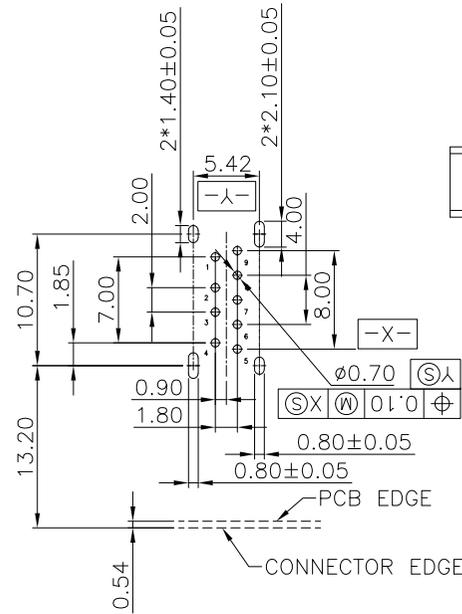
GP Component

REV.	ECN NO.	LOCATIONS	DESCRIPTION	DATE	DESIGN
A0			Initial	2021/10/09	Ken Lin



NOTES:

- * MATERIALS (材質) AND PLATING (電鍍)
SHELL & COVER MATERIAL: SUS201 T=0.3MM
PLATING: 50u" MIN. NICKEL PLATED OVERALL
- * TERMINAL MATERIAL:
5PIN: C2680, T=0.20MM
4PIN: C5210, T=0.20MM
PLATING: Au 15u" PLATED ON CONTACT AREA,
100u" MIN. TIN PLATED ON SOLDER TAIL,
50u" MIN. NICKEL UNDERPLATED OVERALL.
- * HOUSING MATERIAL: LCP BLUE (PANTONE 300C),
HF (RoHS2.0), UL94V-0
- ELECTRICAL PERFORMANCE (電氣性能)
* RATED VOLTAGE: DC 5.0V
* RATED CURRENT: 1.8A FOR PIN1 & PIN4
0.25A FOR OTHER PINS.
* INSULATION RESISTANCE: 100MΩ MIN. 500V DC,
TEST TIME: 1 SEC. MIN.
* DIELECTRIC WITHSTANDING VOLTAGE: 100V AC,
TEST TIME: 1 SEC. MIN.
* CONTACT RESISTANCE: 30MΩ MAX. FOR PIN1 & PIN4
50MΩ MAX. FOR OTHER PINS.
- ENVIRONMENTAL PERFORMANCE (環境性能)
* OPERATING TEMPERATURE: -20° C TO +85° C
* STORAGE TEMPERATURE: -20° C TO +60° C,
RELATIVE HUMIDITY (%): 20% TO 70%
* STORAGE LIFE: 6 MONTHS MAX.
* SALT SPRAY TEST: 24H FOR SOLDER TAIL,
48H FOR OTHER AREA
- MECHANICAL PERFORMANCE (機械性能)
* DURABILITY: 5000 CYCLES
* INSERTION FORCE: 35N MAX.
* EXTRACTION FORCE: 10N MIN.
* THE PEAK OF TEMPERATURE ON SOLDERING: PIP: 260±5° C 60S.



MATRIX USB **MUSB 09 - 15 - 634** Series number

Pin Number

Plating
01: Gold Flash
15: 15u"
30: 30u"

RECOMMENDED PCB LAYOUT
(COMPONENT SIDE)
ALL TOL IS ±0.05

Pin Number	Signal Name	Pin Number	Signal Name
1	VBUS	5	SSRX-
2	D-	6	SSRX+
3	D+	7	GND
4	GND	8	SSTX-
Shell	Shield	9	SSRT+



Matrix Electronics Co., Ltd
深圳市越洋達科技有限公司

TOLERANCE: X.X ±0.50 X.XX ±0.40 X.XXX ±0.30 X.XXX ±0.15 ANGLE: ±3°	DESIGN BY : KEN LIN	DATE : 2021/10/09	PART NAME: USB3.2 GEN2 TYPE-A DIP 母座/側插式
APPROVED BY1: Richard Hsieh	CHECKED BY: Vicky Hsieh	DATE : 2021/10/09	PART NO. MUSB09-15-634
APPROVED BY2: Richard Hsieh	DATE : 2021/10/09	MOLD NO. NA	DRAW NO.
SCALE: 1:1	SIZE: A4	SHEET NO. 1 OF 1	